

The MA31753 Direct Memory Access Controller (DMAC) is a peripheral interface circuit design primarily for use with the MA31750 microprocessor. Each DMAC provides up to four independent, prioritised channels each of which can perform DMA transfers between memory and/or I/O devices using the MA31750 bus. Each channel has its own programmable internal priority and can be masked under program control. Further, individual channels have their own associated status and control words enabling an individual channel to be re-programmed without disturbing transfers which may be taking place on other channels. Three basic transfer modes are available:

- Direct Memory to I/O peripheral transfers,
- Direct I/O to Memory transfers,
- Memory to Memory transfers,
- I/O to I/O transfers.

The MA31753 interfaces directly to the MA31750 bus, directly supporting on chip parity generation and supporting expanded memory via an MA31751 MMU with either 1 MWord (1750A mode) or 16MWords (1750B mode) of logical memory.

The MA31753 uses System memory to hold address and count information for each transfer. Once this information has been prepared by the processor the DMAC can conduct a number of transfers without further processor intervention.

FEATURES

- Radiation Hard CMOS SOS Technology
- Four Independent DMA Channels
- MIL-STD-1750A or B Operation in an MA31750 System
- Capable of Processor Independent Table Driven Operation
- Memory to Memory, I/O to Memory, Memory to I/O and I/O to I/O Transfers Supported
- Masking of Individual Channel DMA Requests
- Simple MA31750 Bus Interface
- Single Word, Double Word or Multi-Word Transfers for each of the DMA Channels
- Cascade Interface Allows for Channel Expansion
- Programmable Channel Priority
- Parity Checking Available

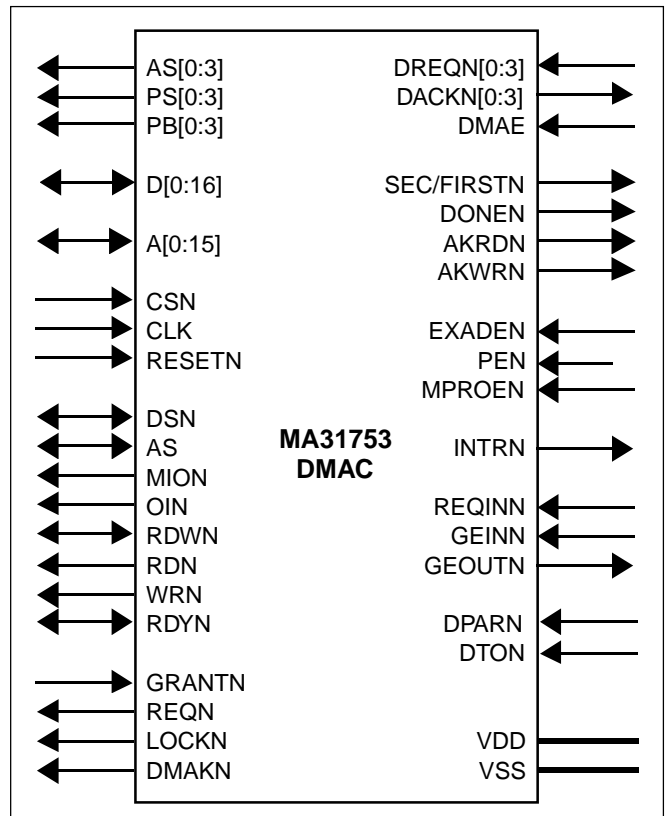


Figure 1: Pin Connections - Top View

1.0 GENERAL DESCRIPTION

The MA31753 DMA controller has 4 channels from which independant transfers can be executed. These channels have programmable priorities and can be masked. They can also be enabled and disabled under software control.

The data can be transferred in several modes - single word mode, double word mode and burst mode. It can be transferred to and from both incrementing and decrementing memory and IO addressing space. The single and double word modes transfer data in 1 or 2 bus cycles when the simple handshaking mechanism is enabled.

If more than 4 channels are required, several DMA controllers can be cascaded together to give channel expansion.

Once a channel has requested a transfer, and the bus arbiter has granted bus control to the DMA, then the DMA issues an acknowledge signal to the channel to be serviced. It also pulses read or write strobes which can be gated with the channel acknowledge signal to provide read and write strobes for the requesting hardware.

DMA instructions can be programmed into memory on the DMA. The transfers defined by these instructions can be executed in sequence if they are "chained together". In this way, DMA transfers can take place continuously with data that is held in seperate memory areas.

There is software access to all internal registers. These registers have parity protection. By setting certain bits in registers, requests can be initiated for area to area transfers on channels 0 and 1. Interrupts for each channel can also be issued.

2.0 INITIALISATION

After RESETN has been removed the DMA is automatically initiated to be disabled with odd parity, the channel priority order is 0, 1, 2, 3, C (C is the cascaded input) and all channels are masked. At this point, before the DMA is used further, the DMA instructions should be programmed into the DMA internal RAM. Once all the instructions needed are in place, the common features (ie. features that apply to all channels) on the DMA can be programmed. These features should be initialised to the users requirements.

The bus parity may be changed immediately after RESETN goes inactive when the MA31750 reads the configuration word ie. When the DMA detects the XIO address 0x8410, it snoops the data bus and latches the parity bit into an internal copy. This internal copy can later be changed by writing to the DMA Mode / Status register.

The DMA enable / disable follows the DMAE input - when this input is high, the DMA device is enabled. When DMAE is low, the DMA is disabled.

The channel priority and masking can be changed by writing to the DMA Mode / Status register.

Once the common characteristics of the DMA have been set up, the DMA individual channels can be programmed. Each channel has a mode register that should be programmed with an instruction number as that channel is activated (by writing the mode word).

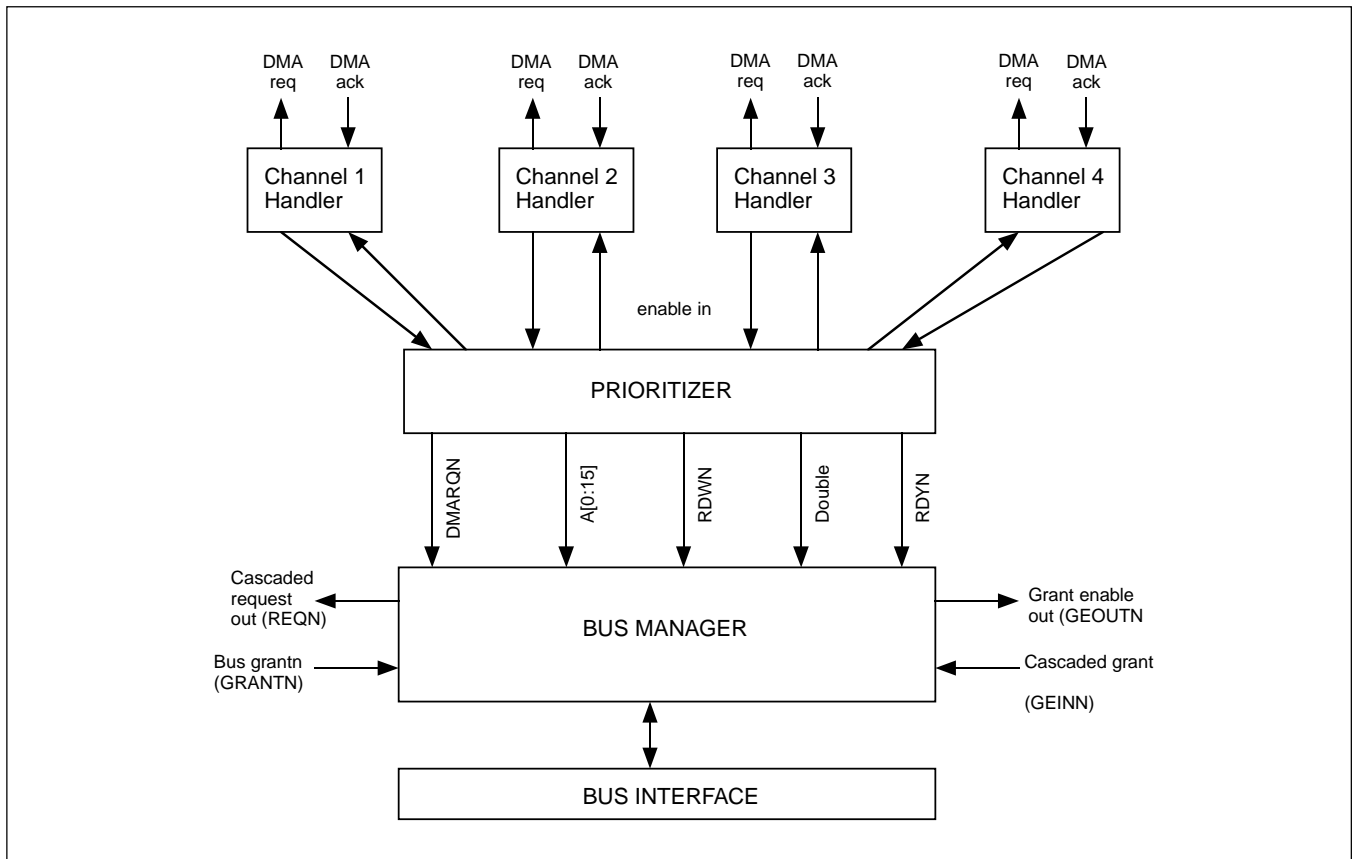


Figure 2: Block Diagram Representing the DMA Controller

3.0 DMA FUNCTIONALITY

Figure 2 shows a block diagram representing the structure of the DMA controller. This figure also shows how the DMA interfaces with the rest of the system.

Each DMA channel has 6 possible modes that it can operate in. These are as follows:

3.1 IDLE MODE

The channel goes into IDLE mode after an active hardware reset or after resetting the status flags. When in IDLE mode, the channel goes into PEND_CHAIN mode when activated by writing the Mode register. No parity check is done on this register write.

3.2 PEND_CHAIN MODE

Once the channel has been activated, it goes from IDLE to PEND_CHAIN mode. In this mode, the first instruction is read (all 8 words). If a parity error is detected, the channel goes to the ERROR mode. If the read is successful, the channel will stay in the PEND_CHAIN mode until either an active request is received or the Channel Request Pending bit is set in the Channel Status Register. At this time, the channel progresses to the PEND_REQ mode.

3.3 PEND_REQ MODE

In this mode, the Mode / Link word is checked to make sure it doesn't de-activate the channel (sending the device back to IDLE mode). If the channel remains active, the device sits in PEND_REQ mode until the system bus arbiter grants the DMA bus control. Once this occurs, the transfer commences and the DMA enters TRANSFER mode.

3.4 TRANSFER MODE

If at any time during the transfer an error occurs, the channel is set into ERROR mode. If the transfers are clean of errors, then the behaviour of the device is dependant on the type of transfer mode that was programmed by the currently executing instruction.

3.4.1 Single/Double Word and External Area to Area Mode

Within these modes, the DMA executes each data transfer separately, ie. between each single / double word transfer, the request is removed. The DMA goes back into PEND_REQ mode after each transfer and waits for the next request to be granted.

3.4.2 Burst Area to Area Mode

With this type of transfer, the DMA transfers data whilst the bus control is granted. The channel request signal remains active. When control is removed by the arbiter, the device sits in the PEND_TRANS mode until re-granted. If the burst mode is area to area with interval timing, then between each transfer, the channel has to count the interval.

Once a transfer has completed, the channel either sets the EOT bit and sits waiting for this to be reset before it goes back into INIT mode, or the instruction is chained and the channel jumps back to the PEND_CHAIN mode where it can read the next instruction details for the next transfer. If during any transfer mode, the channel is de-activated, the channel goes back to INIT mode. If at any time, an error is detected, the device goes into ERROR mode.

3.5 ERROR MODE

This mode is entered from the PEND_CHAIN mode if a parity error is detected during the instruction register reads. The error mode can also be entered from the TRANSFER mode. This can happen if PEN, MPROEN or EXADEN are activated by trying to access one of the data transfer addresses. An interrupt is generated in this mode. The only way to leave this mode is to reset all the error flags.

3.6 WORD TRANSFER MODES

It is possible to run each channel in single, double, and burst mode transfers.

3.6.1 Single Word Transfer

In single word transfer mode, the generation of each request on a channel causes the DMA controller to issue an external request that lasts for one bus cycle. The request is de-activated before the end of the bus cycle to allow other users to acquire bus control. If the transfer is to or from a device needing longer than one machine cycle (2 CLK cycles) then the cycle can be extended using handshaking of the DMA request and acknowledge lines.

3.6.2 Double Word Transfer

In double word mode, each request on a channel causes the DMA controller to request bus control for 2 machine cycles to allow the transfer of 2 16-bit data words. The data is transferred to consecutive addresses and the bus is locked between each word transfer to protect the transfer. The most significant word to be transferred has the lowest address and is transferred first (following the 1750 standard). The request is de-activated before the end of the second bus cycle to allow other bus users to take control. If an extended cycle is needed, the handshaking mechanism doesn't work in this mode and the RDYN signal must be kept high for as long as required.

3.6.3 Burst Mode

In burst mode, one request to the channel causes the DMA to request bus control for a complete block of data to be transferred. The DMA de-asserts the request line on the last transfer cycle to allow other users to take bus control. Consequently, if the transfers are chained together, the CPU may be able to get bus control between 2 blocks of data transfer. If extended bus cycles are needed, the RDYN mechanism can be used (handshaking does not work in this mode).

3.6.4 Area to Area Mode

In area to area mode, the transfers can be initiated either by external requests or internally generated by the DMA depending on the value in the interval timer (the software generated requests controlled by the interval timer can only be used on channels 0 and 1). Each request makes the DMA request bus control for 2 machine cycles. The transfers can take place to and from IO and / or memory depending on how the instruction programs the channel. The DMA de-asserts the request during the second cycle unless the instruction has programmed the channel to do "Continuous Internal Request". In this case, the request is only de-asserted on the last cycle of the block. If extended bus cycles are needed, the RDYN mechanism must be used as the handshaking does not work in this mode.

3.6.5 Instruction Chaining

When the first request is received on a channel, it accesses the DMA instruction number that is programmed in the mode word. This instruction is read from internal DMA RAM. This takes 16 CLK cycles (as there are 8 16-bit word in the instruction). Bus control is not needed during these internal RAM accesses. At the end of the 16 CLK cycles, the channel has all the transfer information it needs and can begin to transfer whenever it is granted bus control. Once the transfer has completed, the channel checks that it is in chaining mode and that the instruction is a chained instruction. If so, then as the first instruction completes, the DMA can access the next instruction (again taking 16 CLK cycles) and the transfers can continue as bus control is granted.

3.6.6 Handshaking Mechanism

There is a handshaking mechanism available when using single-word transfer mode. It works as follows:

For a memory read cycle:

- 1: The IO port issues a request.
- 2: The DMA requests and is granted bus control. The DMA starts a memory read cycle. As well as the usual control and strobcs, the DMA also asserts the DACKN low for the channel that it is responding to. The DACKN signal acts as an IO port select.
- 3: Once valid data is available on the data bus ie. RDYN has gone low, the DMA asserts AKWRN low. The IO port uses AKWRN as a write strobe.
- 4: The IO port acknowledges the completed data read by de-asserting DREQN.
- 5: When the DMA sees DREQN has gone high, it de-asserts DACKN. At this time, the data is still valid and the IO port may latch the data on AKWRN rising or any time in between.
- 6: The DMA completes the cycle by de-asserting strobcs etc.
- 7: The wait state generator finally de-asserts RDYN.

For a memory write cycle:

- 1: The IO port issues a request.
- 2: The DMA acquires bus control and starts a memory write cycle, also asserting DACKN for the relevant channel.
- 3: The data bus is driven by the IO port. Valid data is available when the IO port de-asserts DREQN. (DACKN is still asserted so valid data must still be driven on the bus).
- 4: When the DMA senses DREQN high, it writes the valid data from the IO port into memory.
- 5: The memory write is completed when RDYN goes low.
- 6: The DMA de-asserts DACKN and hence the IO port stops driving the data bus.

If DREQN is de-asserted 2 or more CLK cycles before AKRDN or AKWRN are asserted, then the handshaking protocol does not apply and the cycle will simply use the RDYN signal going low to terminate the cycle (both AKRDN and AKWRN will rise as AS falls at the end of the cycle).

3.7 INTERRUPT GENERATION

The DMA shall generate an interrupt on the occurrence of any of the following:

- A channel has reached an "End of Transfer" condition and the EOT bit has been set in the channel status register.
- A channel has been stopped because
 - a) a bus timeout has occurred. (ie. either DREQN (handshake mode) or RDYN is asserted for more than 256 CLK cycles)
 - b) an internal parity error was detected when reading a DMA register with parity.
 - c) An odd block length was programmed in double word mode.

The DMA will stop but will not generate an interrupt if EXADEN, MPROEN or PEN are active at the end of an external cycle.

If a parity error is detected whilst writing to the DMA registers, the erroneous write will not let transfers commence. The DMA generates interrupts by pulsing INTRN low. If more than one error occurs simultaneously, INTRN is only pulsed once. The interrupt can only be generated when the DMA is in the ERROR mode. The only way to get out of this mode is to reset all error flags.

3.8 CHANNEL MASKING AND STOPPING

Each channel can be masked individually by setting the relevant bit in the DMA Mode / Status register. If the channel is masked, only external requests are gated out - software requests are still serviced.

Each channel can be stopped by de-activating the channel by writing the Channel Mode register. This register can only be written whilst in PEND_CHAIN mode or awaiting bus control. Once the channel is de-activated, it returns to the IDLE mode.

3.9 PARITY CHECKING

Parity checks are done when DMA registers are being written and when they are being accessed ie. when the instructions are being read.

3.10 SOFTWARE PROGRAMMING

DMA requests can be generated in software by writing the CRQP bit in the Channel Status register. If the channel is active, the DMA will then request bus control. If the DREQN signal on that channel is not active, the DMA finishes the cycle as soon as the memory is ready. There is no handshaking with the IO port. DACKN is deasserted when the memory is ready. If DREQN is asserted but is masked, the handshaking is active and operates normally.

Interrupts can be generated in software by setting either a channel EOT flag or any error flag. This can only be done when the DMA is in PEND_CHAIN mode. If an error flag is set, the device goes straight to ERROR mode. If the EOT flag is set, the device looks as if it has completed the transfer. It will then just sit and wait for the EOT flag to be cleared before entering IDLE mode. If both flags are set simultaneously, the device remains in PEND_CHAIN mode. Setting an error flag when EOT is set resets EOT and the device goes to ERROR mode. Setting EOT when an error flag is set clears the error and the DMA sits in the finish transfer mode.

3.11 CASCADING DMA CONTROLLERS

DMA controllers are cascaded in series. For each DMA added, an extra 4 channels become available. To cascade the devices, the strobes, control signals and address and data busses are connected in parallel. Of the bus arbitration signals, LOCKN and GRANTN should be connected in parallel and REQINN, GEINN and GEOUTN should be daisy-chained. INTRN and PEN can either be ORed together with external glue logic or input to separate CPU interrupts. Figure 3 shows the cascade connections.

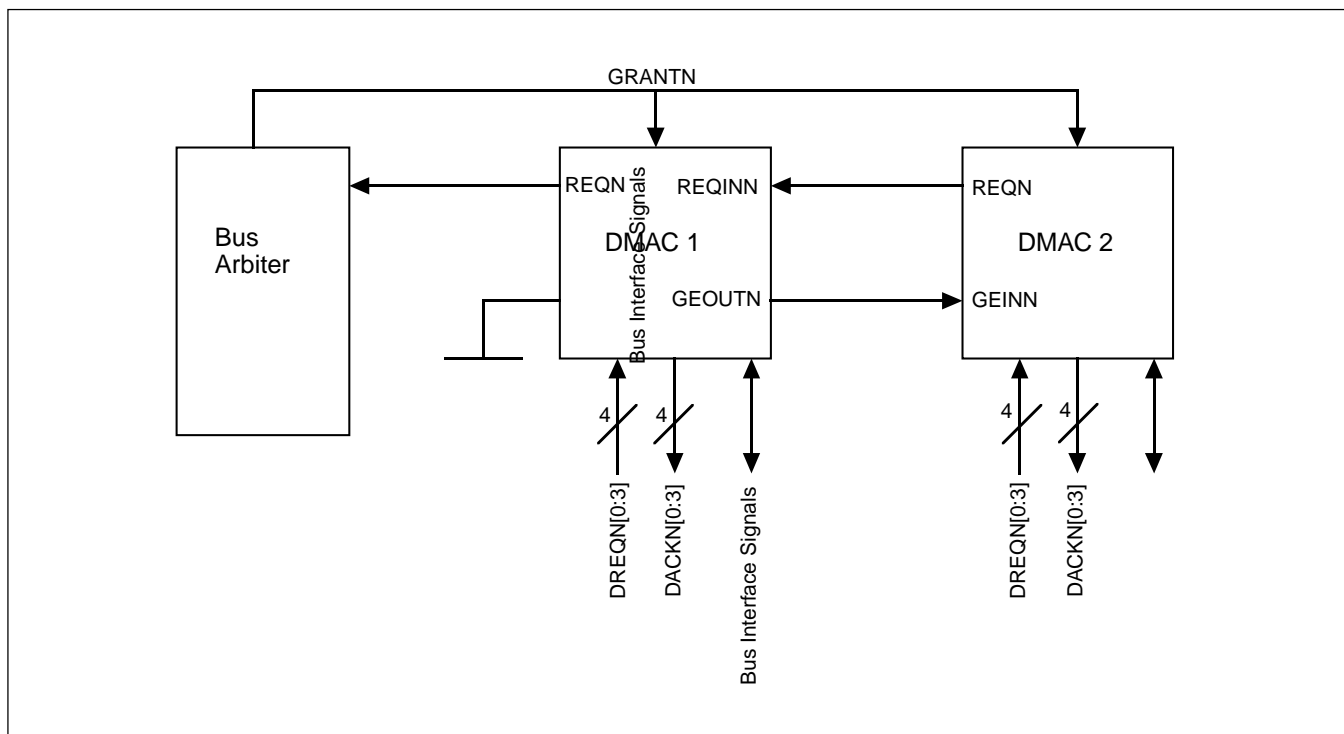


Figure 3: Cascading DMA Controllers

4.0 DETAILED REGISTER DESCRIPTION

The internal registers on the DMA controller can be located in either memory or IO addressing space. 32 words are control registers and 480 words are the DMA instruction registers.

The address lines A[7:15] are used to decode the registers. (A[0:6] are decoded to generate CSN low ie. the user can place the DMA on the address map.)

A[7:15]	Register Content	Parity
0	DMA Instruction	Yes
.	.	.
.	.	.
1DF	DMA Instruction	Yes
1E0	Channel 0 Mode	No
1E1	Channel 0 Remaining words	No
1E2	Channel 0 Area 1 current address	No
1E3	Channel 0 Area 1 current PB/AS/PS	No
1E4	Channel 0 Area 2 current address	No
1E5	Channel 0 Area 2 current PB/AS/PS	No
1E6	Channel 0 Status	No
1E7	DMA Mode / Status 1	No
1E8	Channel 1 Mode	No
1E9	Channel 1 Remaining words	No
1EA	Channel 1 Area 1 current address	No
1EB	Channel 1 Area 1 current PB/AS/PS	No
1EC	Channel 1 Area 2 current address	No
1ED	Channel 1 Area 2 current PB/AS/PS	No
1EE	Channel 1 Status	No
1EF	RESERVED	No
1F0	Channel 2 Mode	No
1F1	Channel 2 Remaining words	No
1F2	Channel 2 Area 1 current address	No
1F3	Channel 2 Area 1 current PB/AS/PS	No
1F4	Channel 2 Area 2 current address	No
1F5	Channel 2 Area 2 current PB/AS/PS	No
1F6	Channel 2 Status	No
1F7	RESERVED	No
1F8	Channel 3 Mode	No
1F9	Channel 3 Remaining words	No
1FA	Channel 3 Area 1 current address	No
1FB	Channel 3 Area 1 current PB/AS/PS	No
1FC	Channel 3 Area 2 current address	No
1FD	Channel 3 Area 2 current PB/AS/PS	No
1FE	Channel 3 Status	No
1FF	RESERVED	No

4.1 MODE REGISTERS

- CA read 0: channel not active
write 0: stop channel
read 1: channel active
write 1: start channel
This bit will be set low at an error or EOT condition

- Mode 000: Single Word
001: Double Word
010: Burst Mode
011: Not used (channel not started)
100: Area to Area, Memory to Memory
101: Area to Area, Memory to IO
110: Area to Area, IO to Memory
111: Area to Area, IO to IO

- A1M Area 1 Mode
For single, double and burst modes
00: Read from memory, incrementing address
01: Read from memory, decrementing address
10: Write to memory, incrementing address
11: Write to memory, decrementing address

Area to area mode
00: Area 1 address constant
01: Area 1 address incrementing
10: Area 1 address decrementing
11: Area 1 address constant

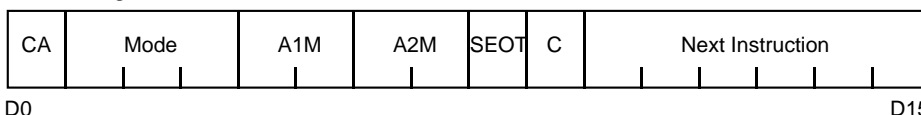
- A2M Area 2 Mode (only used in area to area mode)
00: Area 2 address constant
01: Area 2 address incrementing
10: Area 2 address decrementing
11: Area 2 address constant

- SEOT 0: Signal 'End of Transfer' at end of current block only of C=0
1: Always signal 'End of Transfer' at end of current block.

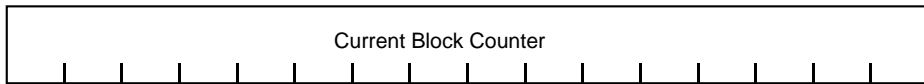
- C read 0: Perform no chaining
read 1: Perform chaining using the value of "next Instruction" field as pointer
write 0: Perform no chaining even if defined by current DMA instruction
write 1: Perform chaining as defined by current instruction

- Next Inst These 6 bits point to one of the 60 DMA instructions ie. the next instruction to be executed.
If the number is 3C, 3D, 3E or 3F, then the transfer will stop with the current block (ie. no chaining)

Mode Register

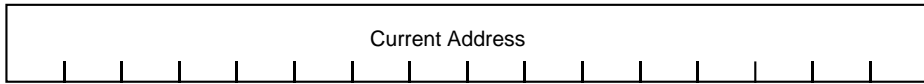


4.2 REMAINING WORD REGISTERS



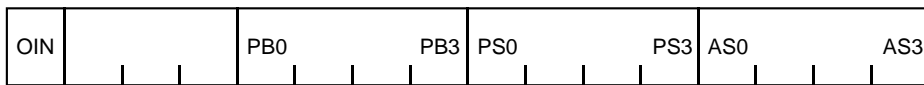
D0 D15
Read access only. These 16-bit registers store the number of words left to be transferred for each area.

4.3 CURRENT ADDRESS REGISTERS



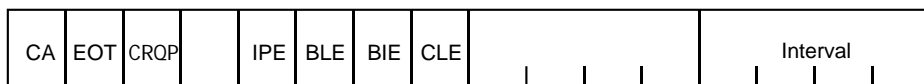
D0 D15
Read access only. These 16-bit registers store the addresses of the current words to be transferred to / from the area represented by the register.

4.4 CURRENT PB / PS / AS REGISTER



D0 D15
Read access only. These 16-bit registers store the current page bank, address and process state information for each area. When the areas have been selected within the IO space, PB, PS and AS shall be zero.

4.5 STATUS REGISTERS



- D0 D15
- CA 0: Channel not active
 1: Channel active
 This bit is automatically set to zero at an error or EOT condition.
 - EOT 0: Channel EOT not reached
 1: Channel EOT reached.
 - CRQP 0: No channel DMA request pending.
 1: Channel DMA request pending.
 It is not possible to reset this bit as long as a DREQN line is asserted.
 - IPE 0: No internal parity error
 1: Internal parity error when reading DMA register with parity.
 - BLE 0: No error
 1: Block length error (odd block length in double word mode)
 - BIE 0: No error
 1: Bus interface timeout error (caused either by not deasserting DREQN in handshake mode or by a bus timeout)
 - CLE 0: No error
 1: CPU latched error (either MPROEN, EXADEN or PEN)
 - Interval The interval, in CLK cycles, between each DMA request generated during area to area transfers.

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4.6 DMA MODE / STATUS 1

M3	M2	M1	M0	EOT3	EOT2	EOT1	EOT0	ERR	A/B		BP	DMAE	Priority
----	----	----	----	------	------	------	------	-----	-----	--	----	------	----------

D0 D15

Mn 0: Channel n not masked
1: Channel n masked

EOTn 0: Channel n "End of Transfer" not reached
1: Channel n "End of Transfer" reached
Read access only. Value can be changed by writing the channel status register.

ERR 0: No error detected
1: Error detected in one or more of the channels
Read access only. Value can be changed by writing the channel status register.

A / B 0: 1750A mode
1: 1750B mode

BP 0: Even bus parity used
1: Odd bus parity used

DMAE 0: DMA requests disabled
1: DMA requests enabled
Read access only

Pri 000: Channel priority 0, 1, 2, 3, C
001: Channel priority 1, 2, 3, 0, C
010: Channel priority 2, 3, 0, 1, C
011: Channel priority 3, 0, 1, 2, C
100: Channel priority C, 0, 1, 2, 3
101: Channel priority C, 1, 2, 3, 0
110: Channel priority C, 2, 3, 0, 1
111: Channel priority C, 3, 0, 1, 2

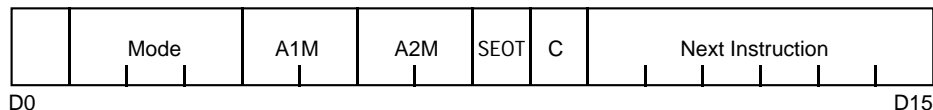
5.0 DMA INSTRUCTIONS

60 DMA instructions are present in the memory or IO space between $A[7:15] = 0$ and $A[7:15] = 1DF$. Each DMA instruction comprises of 8 16-bit words. The base address for each instruction is $8*n$ where n is the instruction number. The instructions are structured as below:

Word number	Content
0	Mode/Link word
1	Block length
2	Area 1 base address
3	Area 1 PB, PS and AS
4	Area 2 base address
5	Area 2 PB, PS and AS
6	Transfer interval
7	Not used

Words 4, 5 and 6 are used only during area to area mode transfers. Word 6 can only be used for channels 0 and 1.

5.1 MODE / LINK WORD



- Mode**
- 000: Single word
 - 001: Double word
 - 010: Burst mode
 - 011: not used (channel not started)
 - 100: Area to Area, Memory to Memory
 - 101: Area to Area, Memory to IO
 - 110: Area to Area, IO to Memory
 - 111: Area to Area, IO to IO

- A1M Area 1 Mode**
 For single, double and burst modes
- 00: Read from memory, incrementing address
 - 01: Read from memory, decrementing address
 - 10: Write to memory, incrementing address
 - 11: Write to memory, decrementing address

- Area to area mode**
- 00: Area 1 address constant
 - 01: Area 1 address incrementing
 - 10: Area 1 address decrementing
 - 11: Area 1 address constant

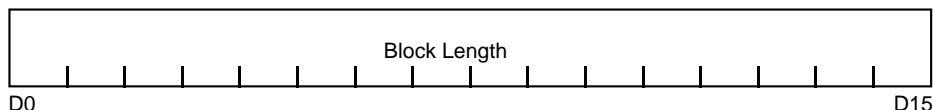
- A2M Area 2 Mode (only used in area to area mode)**
- 00: Area 2 address constant
 - 01: Area 2 address incrementing
 - 10: Area 2 address decrementing
 - 11: Area 2 address constant

- SEOT**
- 0: Signal 'End of Transfer' at end of current block only of C=0
 - 1: Always signal 'End of Transfer' at end of current block.

- C**
- read 0: Perform no chaining
 - read 1: Perform chaining using the value of "next Instruction" field as pointer
 - write 0: Perform no chaining even if defined by current DMA instruction
 - write 1: Perform chaining as defined by current instruction

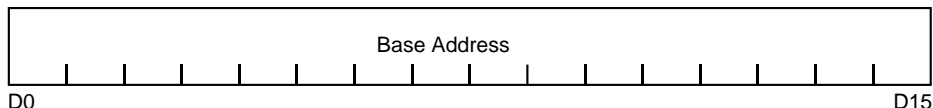
Next Inst These 6 bits give the number of the next instruction to be executed. If the number is 3C, 3D, 3E or 3F, then the DMA transfers will stop with the current block.

5.2 BLOCK LENGTH



This readable and writable 16-bit word gives the number of words to be transferred for the current DMA block.

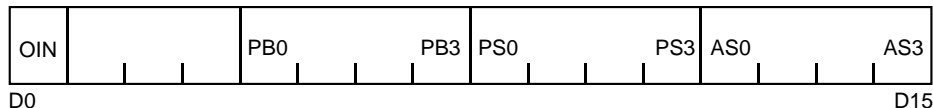
5.3 AREA 1 AND 2 BASE ADDRESSES



These registers hold the addresses of the first word of memory or IO to be transferred (ie. when the channel is decrementing the address, this register holds the highest address to be transferred.)

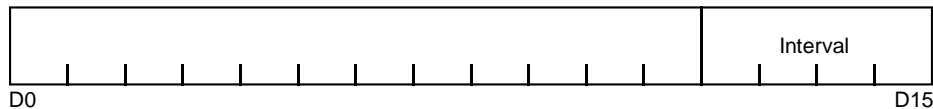
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5.4 AREA 1 AND 2 PB, PS AND AS



These readable and writable registers store the Page Bank, Processor and Address State information to be used when accessing areas 1 and 2. When areas are defined within IO space, PB, PS and AS are set to zero.

5.5 TRANSFER INTERVAL



This readable and writable register gives the number of CLK cycles between each DMA request generated during area to area transfers. The number entered as the interval value corresponds to a clock cycle interval increasing by 32 as follows:

- 0 => - (externally triggered DMA requests)
- 1 => 0 (continuous DMA requests until the block is completed.)
- 2 => 32
- 3 => 64
- 4 => 96
-
- 14 => 416
- 15 => 448

This function is valid only for transfers on channels 0 and 1. Channels 2 and 3 work only on externally triggered requests.

5.6 CONFIGURATION WORD

The DMA controller snoops the system address bus for the XIO address 0x8410. When this appears, the DMA stores the data bus (qualified by DSN low) in an internal copy of the CPU configuration word.

6.0 PIN DESCRIPTIONS

A[0:15]	I/O	A[0] is the most significant bit of this logical address bus. This bus is an input during cycles not assigned to the DMA and is driven during DMA cycles.
PB[0:3]	O	Used in 1750B mode only, this bus provides DMA page bank information which addresses up to 8M of memory. The bus is tri-stated during cycles not assigned to the DMA.
AS[0:3]	O	This bus indicates the current address state of the DMA controller. It is tri-stated during cycles not assigned to the DMA.
PS[0:3]	O	This bus indicates the current process state of the DMA controller. It is tri-stated during cycles not assigned to the DMA.
D[0:16]	I/O	D[0] is the most significant bit of the data bus. During DMA cycles, data is input on read cycles and output on write cycles. D[16] is the parity bit. Odd or even parity is set in the configuration word. Parity is not used during DMA writes to memory.
CLK	I	Input clock signal
RESETN	I	This active low signal resets the DMA.
CSN	I	When low, access to read and write the DMA internal registers is enabled.
AS	I/O	AS high indicates the presence of a valid address on the address bus. This signal is an input on cycles not assigned to the DMA.
DSN	I/O	When low, data strobe indicates the presence of data on the data bus. This signal is an input on cycles not assigned to the DMA.
MION	I/O	If high, this signal indicates that the current cycle is accessing memory space. If low, the current cycle is accessing IO space. Is an input during cycles not assigned to the DMA.
RDWN	I/O	During DMA cycles, this signal goes high to indicate read cycles and low to indicate write cycles. It is an input during non-DMA cycles.
OIN	O	During DMA cycles, this signal goes high to indicate operand cycles and low to indicate instruction cycles. It is tri-stated during non-DMA cycles.
RDN	O	This active low read strobe is tri-stated on non-DMA cycles.
WRN	O	This active low write strobe is tri-stated on non-DMA cycles.
RDYN	I/O	This signal goes active low to indicate that the current bus cycles can be terminated. It is an output on cycles addressing the DMA internal registers, input on cycles controlled by the DMA and is tri-stated during all other cycles.
LOCKN	O	This signal is driven low during the first bus cycle of a double word transfer. It should be used by the bus arbiter to 'lock' bus control to the DMA. It is tri-stated during cycles not assigned to the DMA.
REQN	O	Always driven, this signal goes low to indicate that the DMA requests the bus.
GRANTN	I	Sampled by the DMA on negative CLK edges, this signal goes low to indicate that the DMA has bus control.
DMAKN	O	This output is driven active low by the DMA when it has bus control. It is tri-stated on cycles not assigned to the DMA.
DONEN	O	This signal is pulsed low for one CLK cycle when any of the four DMA channels reaches an 'end of transfer' condition.
REQINN	I	Sampled by the DMA on negative CLK edges, a low on this input indicates that a cascaded, lower priority DMA is requesting the bus. This input should be tied high in a single DMA system.
GEINN	I	This active low signal is used to qualify the GRANTN signal for cascaded DMA devices. This signal should be tied low on the first DMA of the chain.
GEOUTN	O	This active low output indicates that a lower priority DMA will be granted the bus when the GRANTN signal is asserted low from the arbiter. It is used to cascade DMA devices by connecting to the GEINN pin of the next DMA.
INTRN	O	This active low interrupt request signal pulses low when an 'end of transfer' or an internal error condition are detected.
PEN	I	The DMA samples PEN on AS falling. If an error condition is sampled, the transfer on the DMA channel is stopped and the CLE bit is set in the Channel Status Register.
DMAE	I	An active high input to indicate that the DMA is enabled. If this input is low, internal requests are suppressed, there is no response to external requests and REQINN is gated out internally.
DPARN	I	A low on this signal resets and disables checking of the parity bit (D[16])
DTON	I	A low on this signal resets and disables the bus fault timeout circuitry.
MPROEN	I	This input is sampled on AS falling when the DMA has bus control. If an active low is sampled, the transfer stops on the channel concerned and the CAE (addressing error) bit is set in the channel status register. An interrupt may be generated.
EXADEN	I	This input is sampled on AS falling when the DMA has bus control. If an active low is sampled, the transfer stops on the channel concerned and the CAE (addressing error) bit is set in the channel status register. An interrupt may be generated.
DREQN[0:3]	I	Sampled by the DMA on negative CLK edges, a low on this bus initiates a DMA transfer providing the corresponding channel is correctly set up and is not masked. When the pin is pulled high, the ongoing bus cycle will terminate.
DACKN[0:3]	O	During a transfer, the DMA drives the relevant channel acknowledge low to indicate that the DMA is ready for the data. The low to high transition at the end of the cycle is initiated by the condition DREQN high and RDYN low.
SEC/FIRSTN	O	A high indicates that the first word in a transfer is occurring. A low indicates that the second word in a double word transfer is occurring.
AKRDN	O	This active low strobe indicates that the DMA is driving the data bus.
AKWRN	O	This active low strobe indicates that the DMA is inputting data from the data bus.

TIMING DIAGRAMS

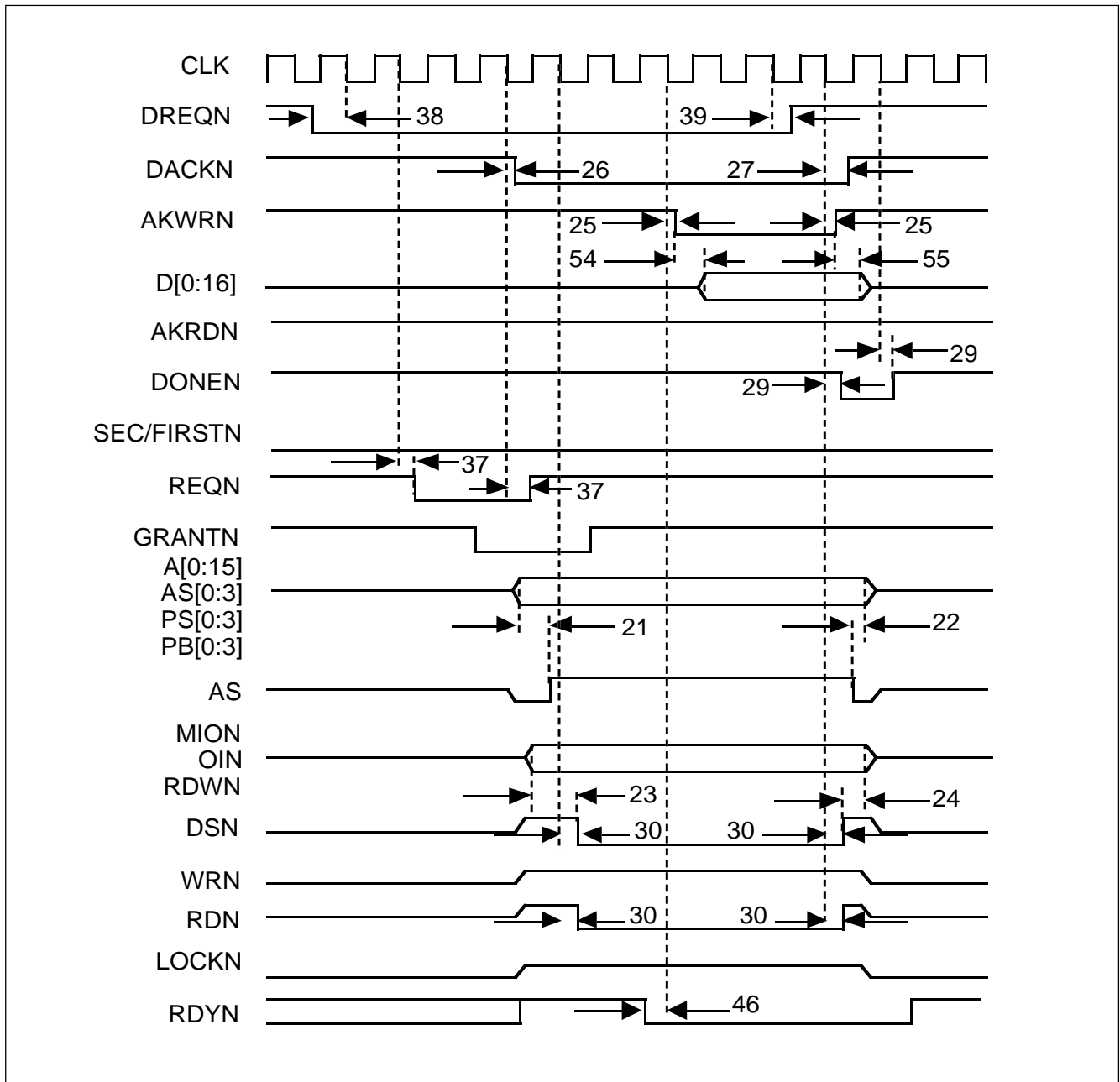


Figure 4: Single Cycle With Handshake, Memory Read

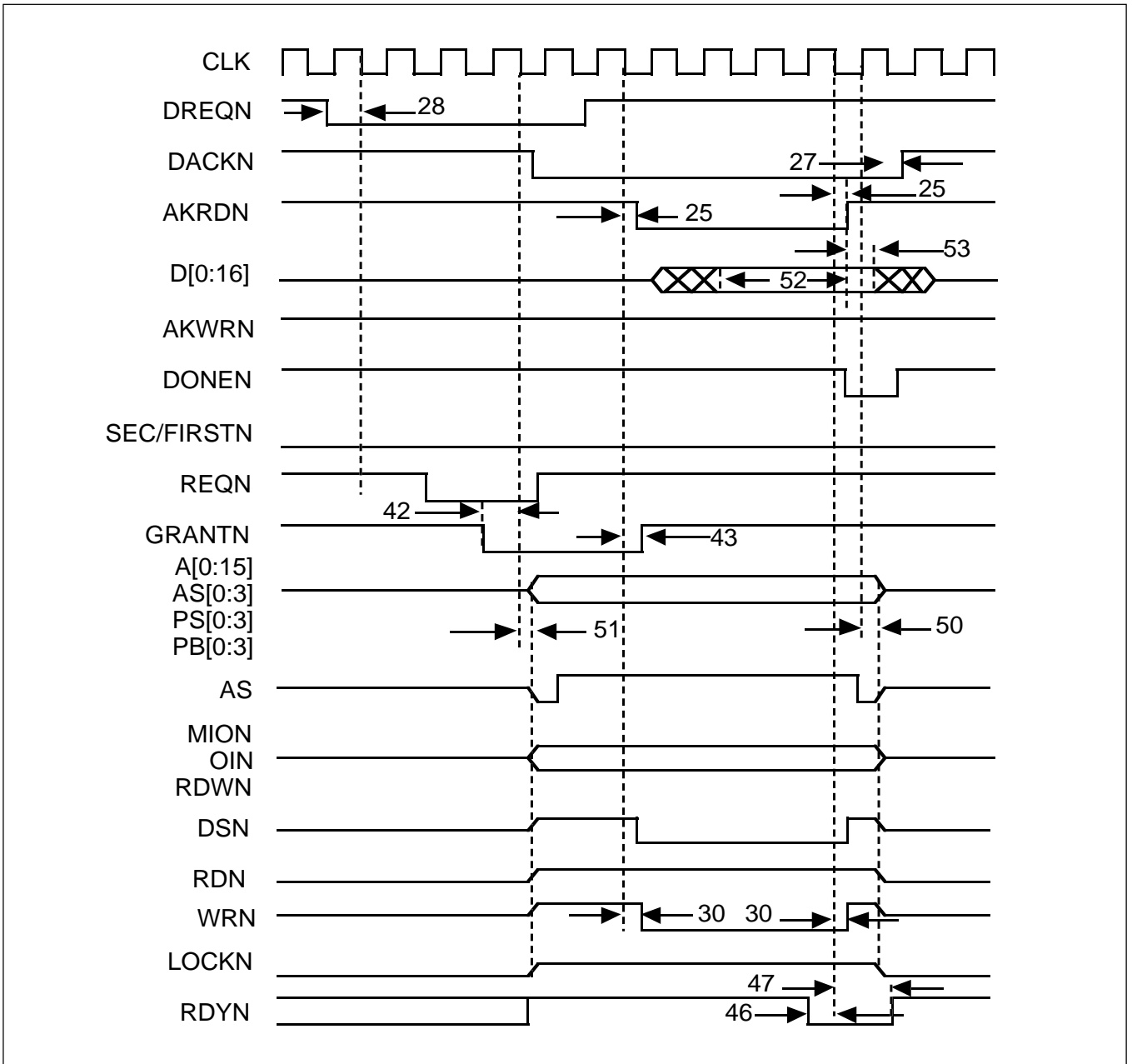


Figure 5: Single Cycle With Handshake, Memory Write

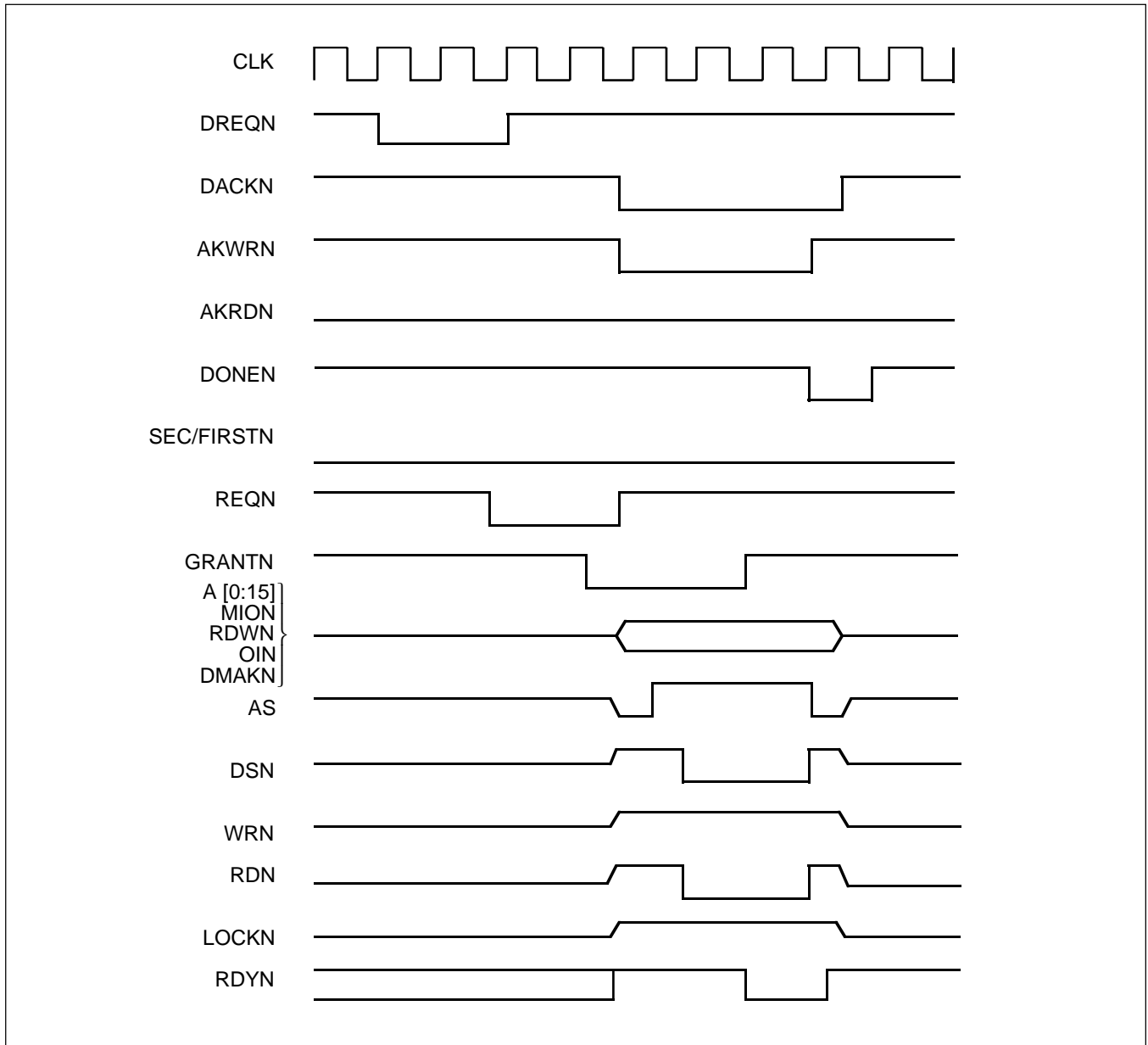


Figure 6: Single Cycle Without Handshake, Memory Read

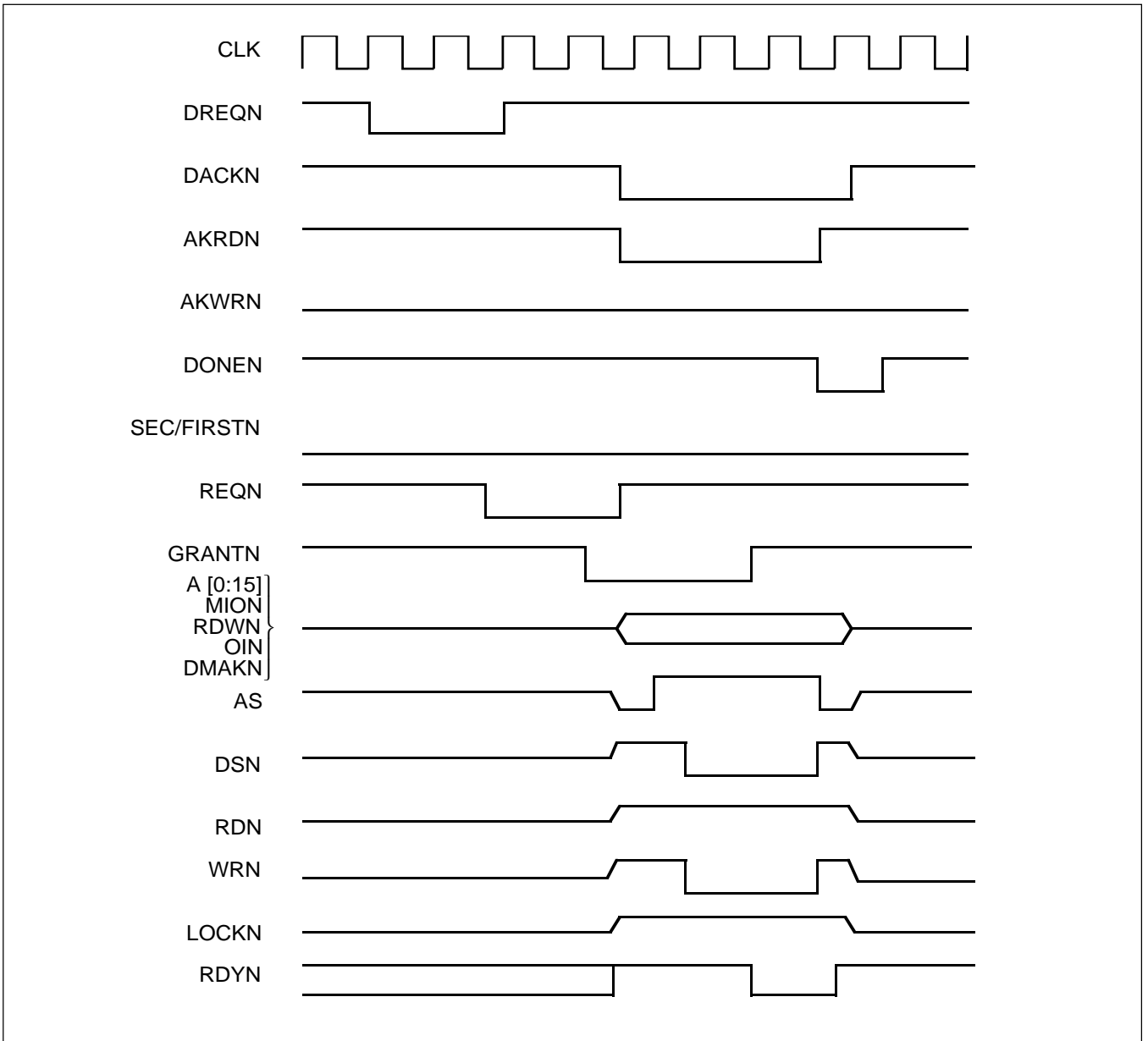


Figure 7: Single Cycle Without Handshake, Memory Write

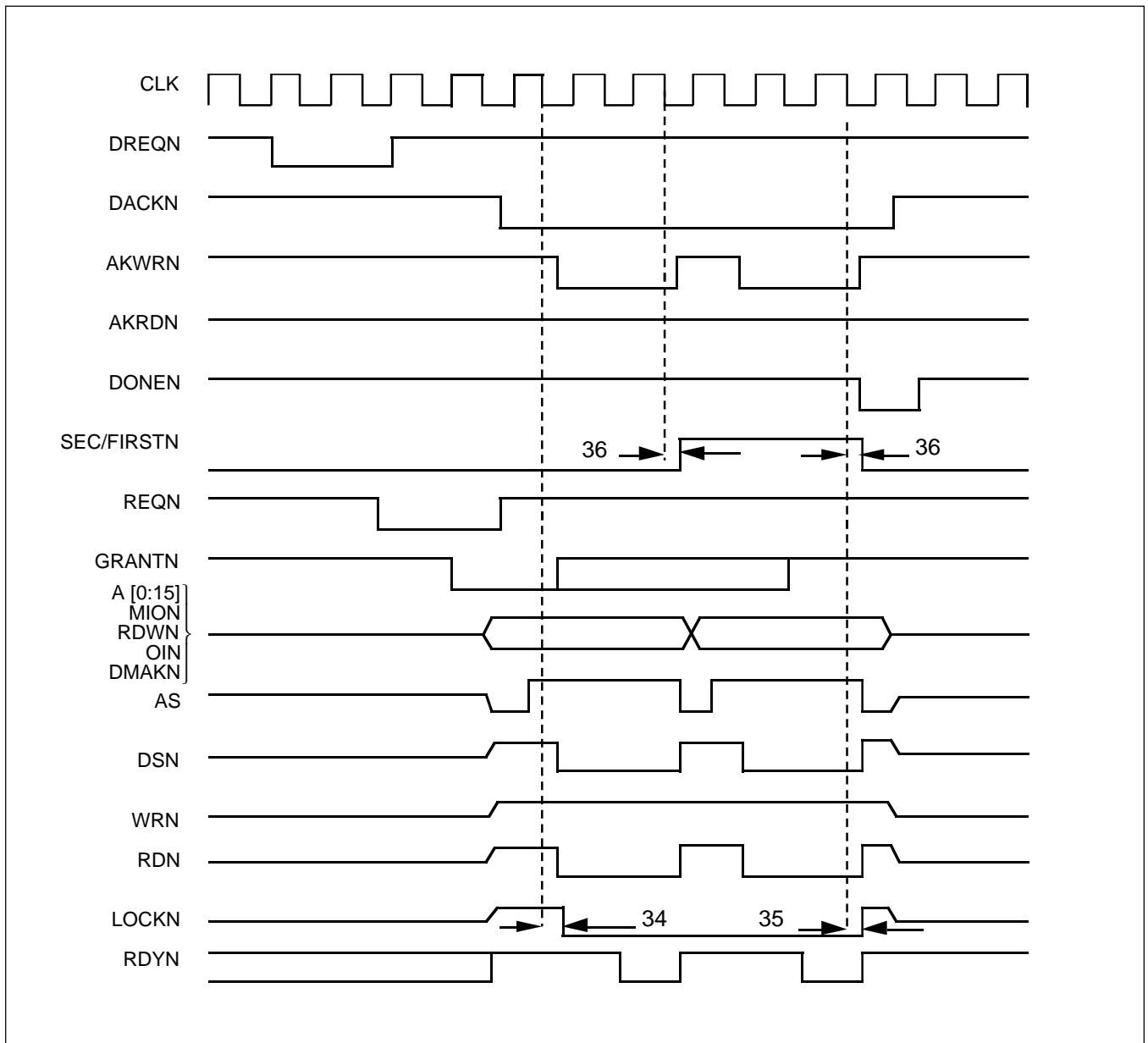


Figure 8: Double Mode, Memory Read

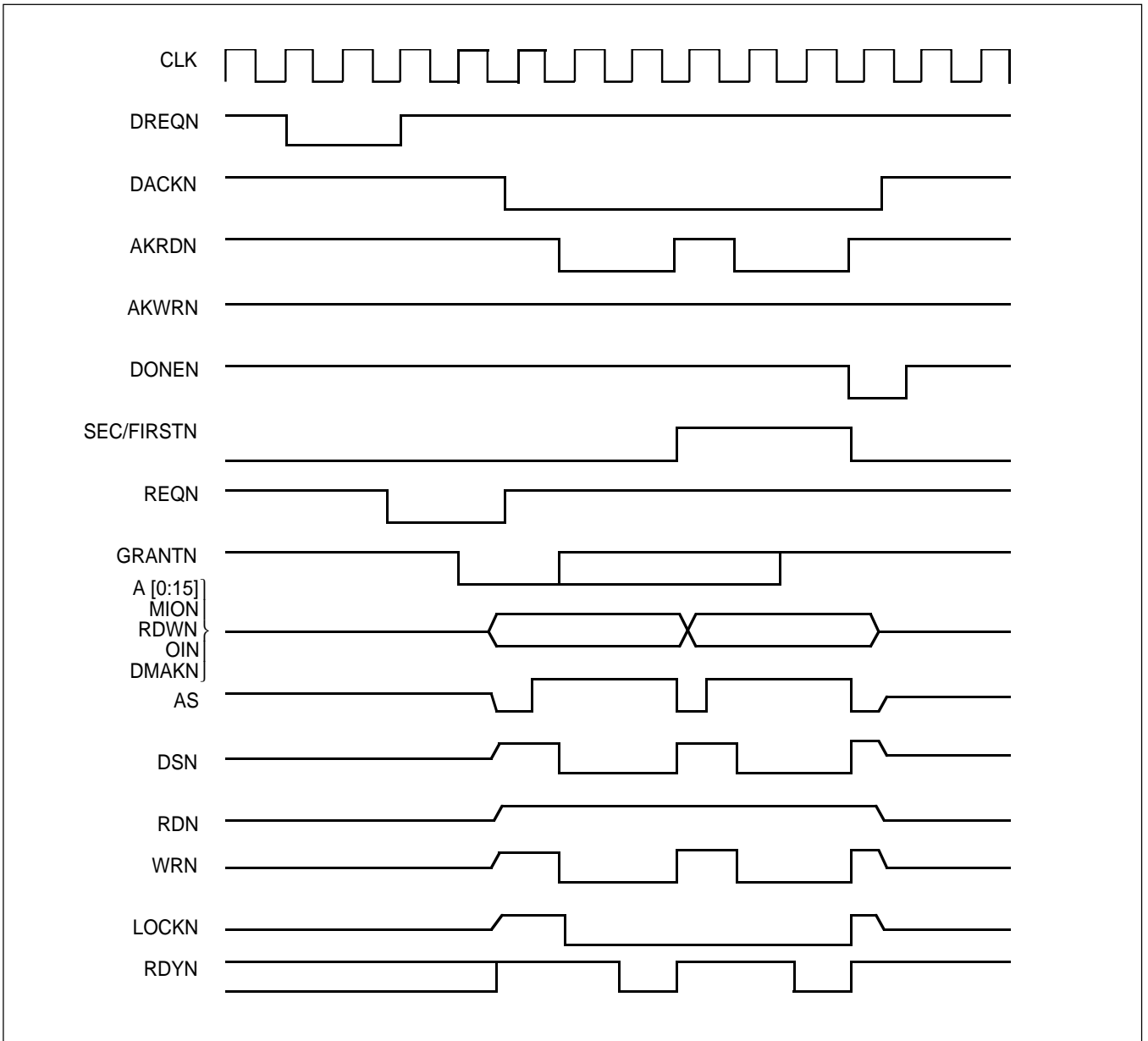


Figure 9: Double Mode, Memory Write

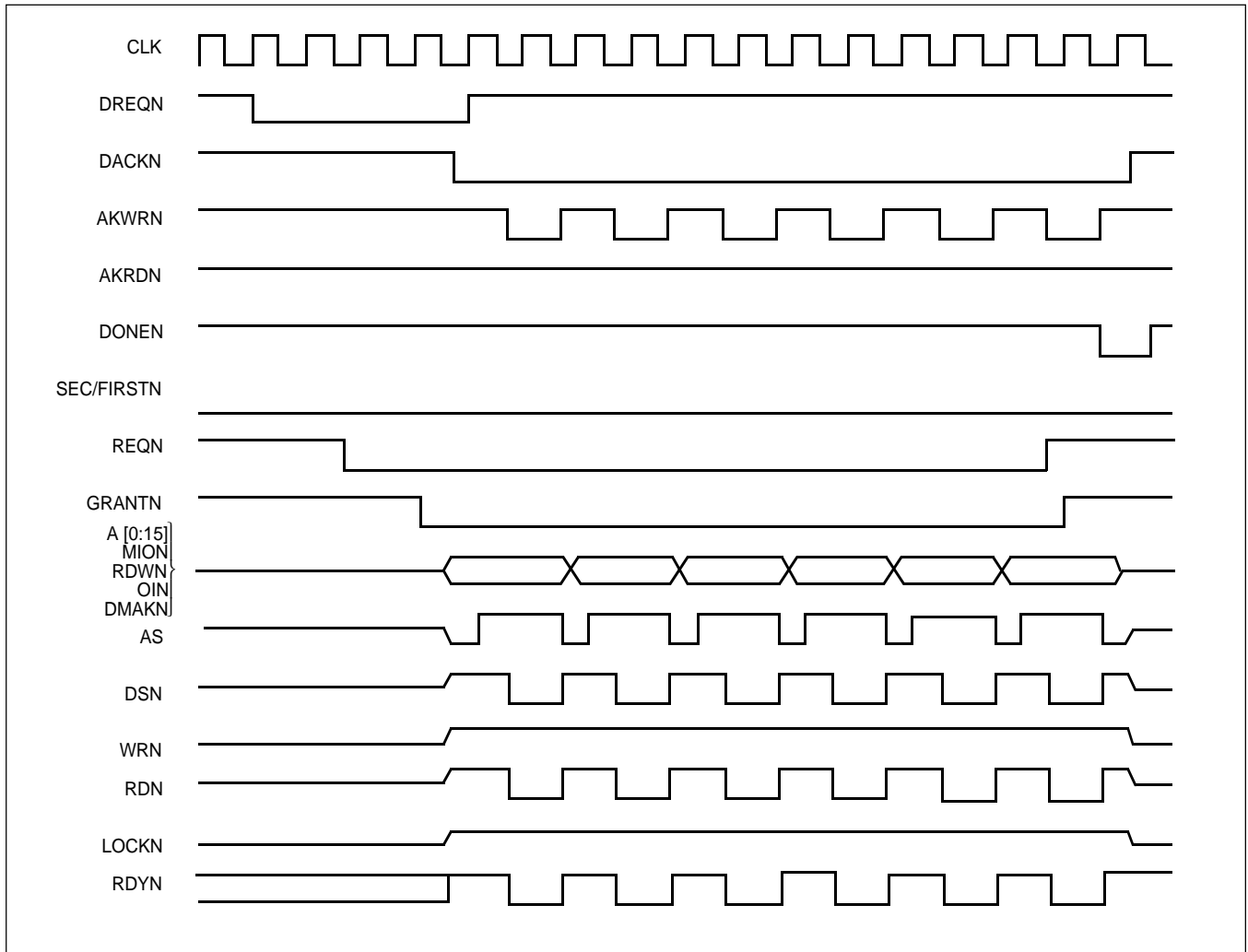


Figure 10: Burst Mode 6 Words, Memory Read

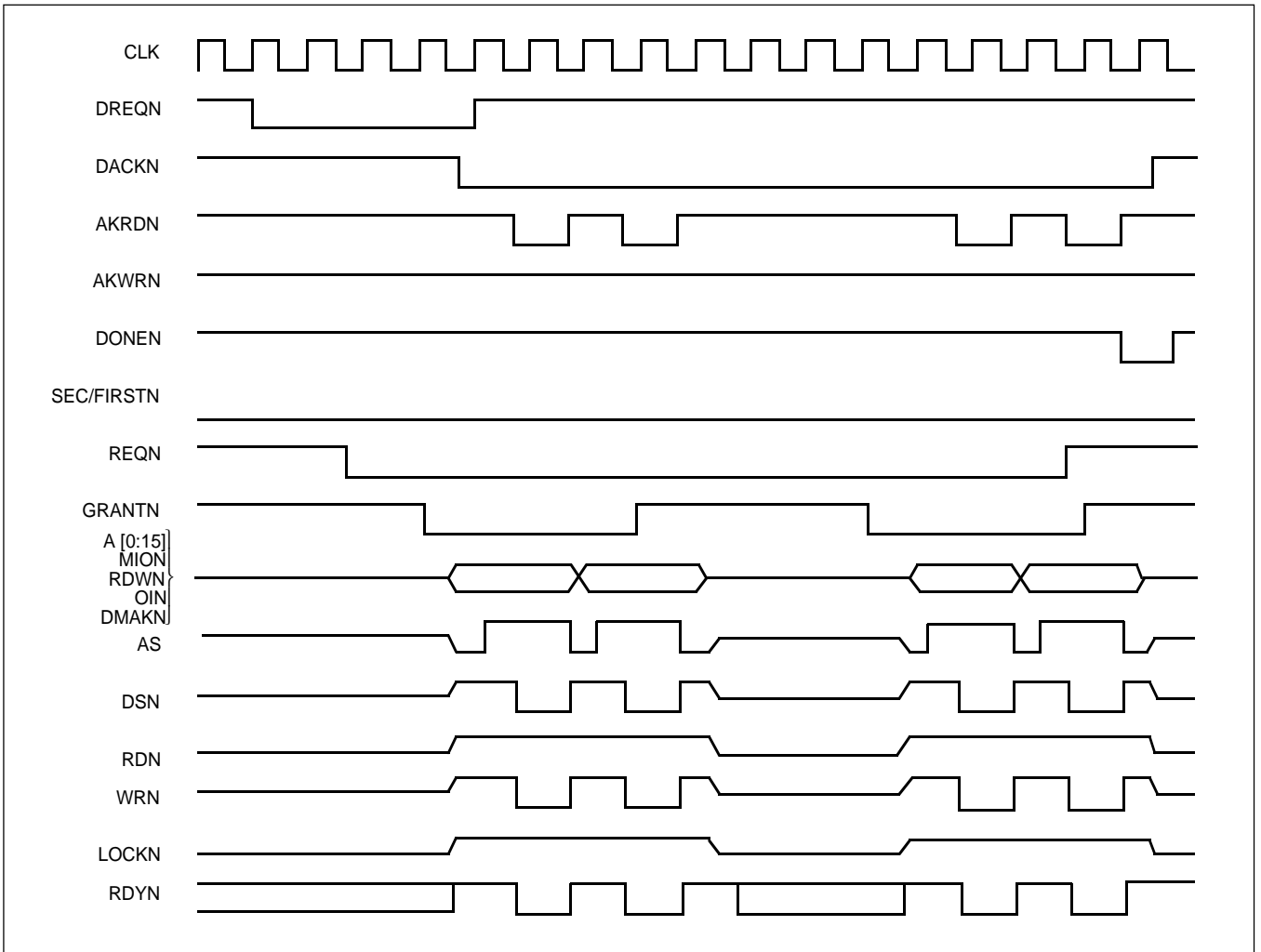


Figure 11: Burst Mode 4 Words, Memory Write (with interruption of the block)

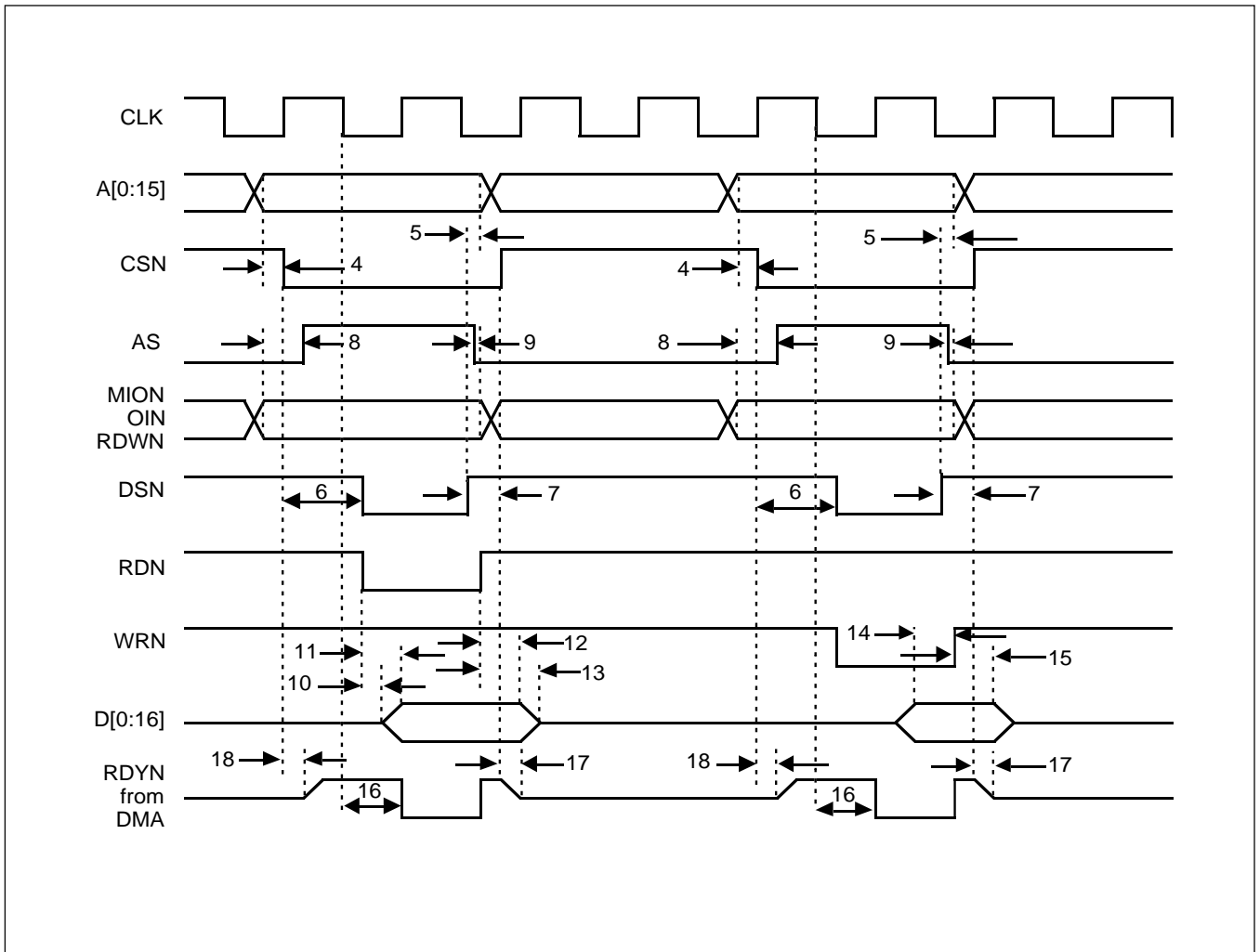


Figure 12: DMA XIO read and write cycles

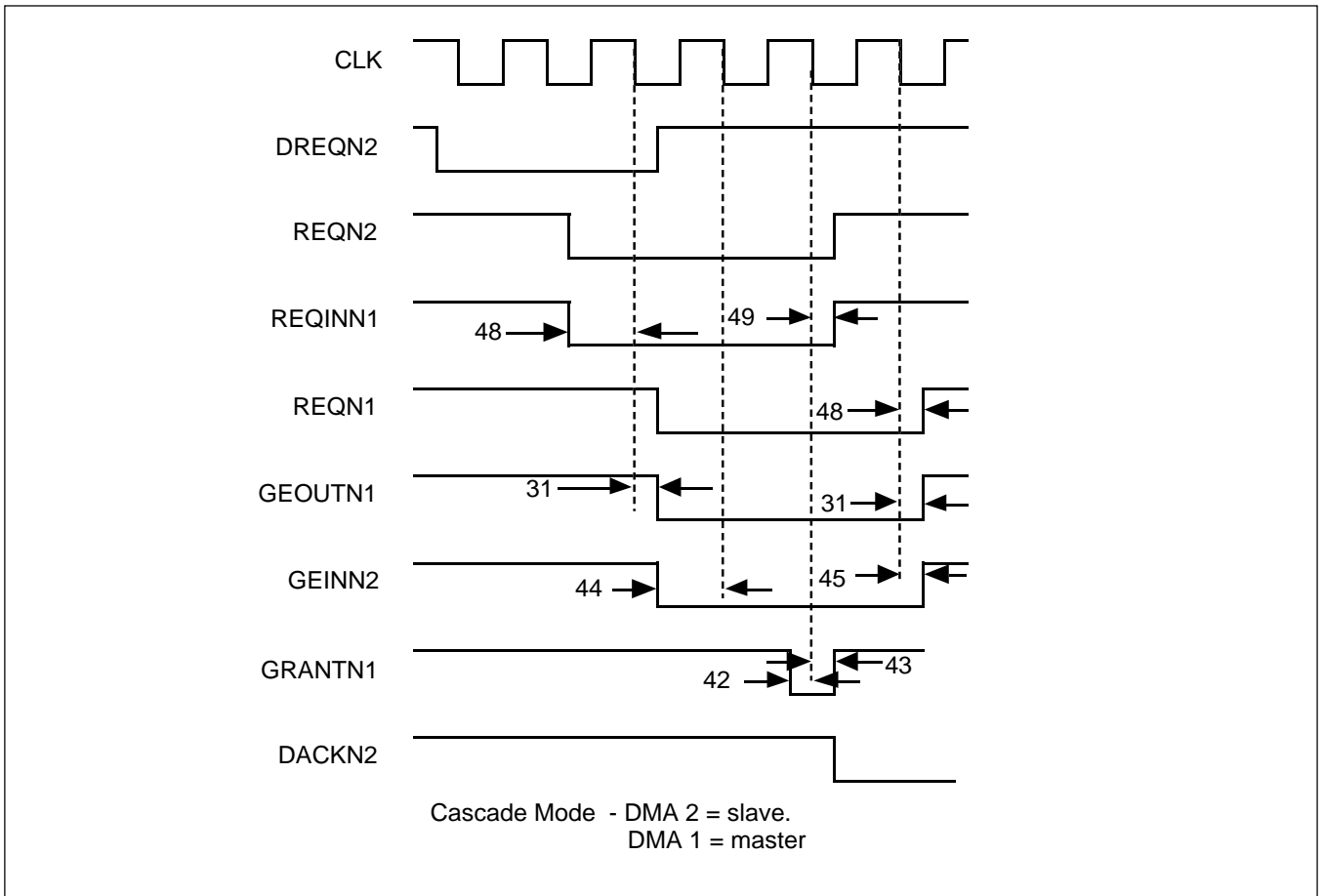


Figure 13: Cascade Mode

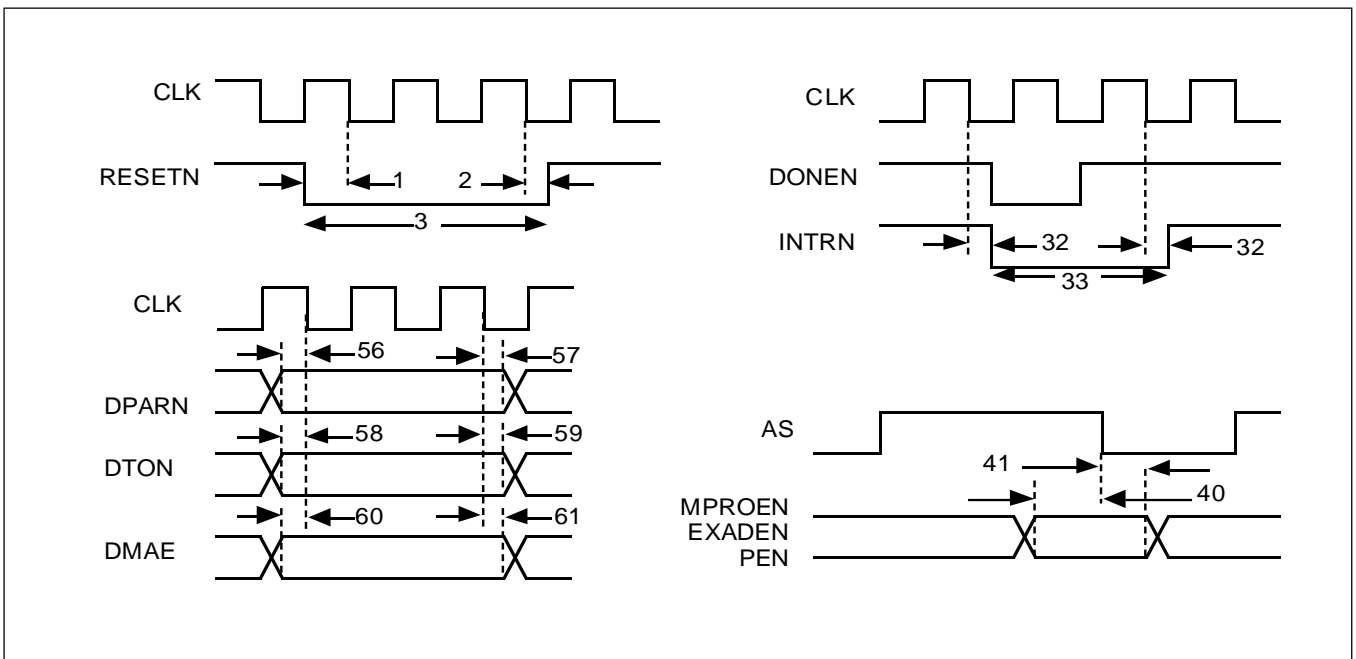


Figure 14: Miscellaneous Timings

MA31753

No.	Description	Min	Max	Units
1	RESETN setup to CLK falling		-	ns
2	RESETN hold after CLK falling		-	ns
3	RESETN pulse width		-	ns
4	A[0:15] setup to CSN falling (DMA XIO)		-	ns
5	A[0:15] hold after DSN rising (DMA XIO)		-	ns
6	CSN setup to DSN falling (DMA XIO)		-	ns
7	CSN hold after DSN rising (DMA XIO)		-	ns
8	MION, OIN, RDWN setup to AS rising (DMA XIO)		-	ns
9	MION, OIN, RDWN hold after AS falling (DMA XIO)		-	ns
10	RDN falling to D[0:16] driven (XIO read)			ns
11	RDN falling to D[0:16] valid (XIO read)			ns
12	RDN rising to D[0:16] invalid (XIO read)			ns
13	RDN rising to D[0:16] tri-state (XIO read)			ns
14	D[0:16] setup to WRN rising (XIO write)		-	ns
15	D[0:16] hold after WRN rising (XIO write)		-	ns
16	CLK falling to RDYN valid (DMA XIO)			ns
17	CSN rising to RDYN tri-state (DMA XIO)			ns
18	CSN falling to RDYN driven (DMA XIO)			ns
19	CLK rising to AS rising			ns
20	CLK falling to AS falling			ns
21	A[0:15], AS[0:3], PS[0:3], PB[0:3] valid to AS rising			ns
22	A[0:15], AS[0:3], PS[0:3], PB[0:3] valid after AS falling			ns
23	MION, OIN, RDWN valid to DSN falling			ns
24	MION, OIN, RDWN valid after DSN rising			ns
25	CLK falling to AKRDN, AKWRN valid			ns
26	CLK falling to DACKN[0:3] falling			ns
27	CLK falling to DACKN[0:3] rising			ns
28	CLK falling to DMAKN valid			ns
29	CLK falling to DONEN valid			ns
30	CLK falling to DSN, RDN, WRN valid			ns
31	CLK falling to GEOUTN valid			ns
32	CLK falling to INTRN valid			ns
33	INTRN pulse width			ns
34	CLK falling to LOCKN falling			ns
35	CLK falling to LOCKN rising			ns
36	CLK falling to SEC/FIRSTN valid			ns
37	CLK falling to REQN valid			ns
38	DREQN[0:3] setup to CLK falling		-	ns
39	DREQN[0:3] hold after CLK falling		-	ns
40	EXADEN, MPROEN, PEN setup to AS falling		-	ns
41	EXADEN, MPROEN, PEN hold after AS falling		-	ns
42	GRANTN setup to CLK falling		-	ns
43	GRANTN hold after CLK falling		-	ns
44	GEINN setup to CLK falling		-	ns
45	GEINN hold after CLK falling		-	ns
46	RDYN setup to CLK falling		-	ns
47	RDYN hold after CLK falling		-	ns
48	REQINN setup to CLK falling		-	ns
49	REQINN hold after CLK falling		-	ns
50	CLK rising to busses, strobes and control signals (note 1) tri-state			ns
51	CLK falling to busses, strobes and control signals (note 1) driven			ns
52	D[0:16] setup to AKRDN rising		-	ns
53	D[0:16] hold after AKRDN rising		-	ns
54	D[0:16] valid after AKWRN falling			ns
55	D[0:16] valid after AKWRN rising			ns
56	DPARN setup to CLK falling		-	ns
57	DPARN hold after CLK falling		-	ns
58	DTON setup to CLK falling		-	ns
59	DTON hold after CLK falling		-	ns
60	DMAE setup to CLK falling		-	ns
61	DMAE hold after CLK falling		-	ns

Mil-Std-883, Method 5005, Subgroups 9, 10, 11.

TL = Low CLK period (ns), TH = High CLK period (ns).

Test Conditions: Vdd = 5.0V ±10%, Temperature = -55°C to 125°C, Vil = 0.0V, Vih = Vdd.

Output loads: All test load 1 unless otherwise specified.

Output Threshold: 50% Vdd (Load 1), Vss+1V, Vdd-1V (Load 2).

Note 1: A[0:15], AS[0:3], PS[0:3], PB[0:3], MION, OIN, RDWN, DMAKN, AS, DSN, RDN, WRN, LOCKN

Figure 15: Timing Parameters

RATING AND CHARACTERISTICS

Parameter	Min.	Max.	Units
Supply voltage	-0.5	7	V
Input voltage	-0.3	VDD+0.3	V
Current through any I/O pin	-20	20	mA
Operating temperature	-55	125	°C
Storage temperature	-65	150	°C

Note: Stresses above those listed may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these conditions, or at any other condition above those indicated in the operations section of this specification, is not implied. Exposure to absolute maximum ratings for extended periods may affect device reliability.

Figure 16: Absolute Maximum Ratings

Parameter	Min.	Max	Units
Clock Frequency (CLK)	0	16	MHz
Recommended Clock duty cycle	45	55	%

V_{DD}=5V±10% over full operating temperature range
Mil-Std-883, method 5005, subgroups 7, 8A, 8B

Figure 17: Operating AC Electrical Characteristics

			Total dose radiation not exceeding 3x10 ⁵ Rad(Si)			
Symbol	Parameters	Conditions	Min	Typ	Max	Units
V _{DD}	Supply voltage	-	4.5	5.0	5.5	V
V _{IH}	Input high voltage	-	80% V _{DD}	-	-	V
V _{IL}	Input low voltage	-	-	-	20% V _{DD}	V
V _{CKH}	CLK input high voltage	-	V _{DD} -0.5	-	-	V
V _{CKL}	CLK input low voltage	-	-	-	V _{SS} +0.5	V
V _{OH}	Output high voltage	I _{OH} =-3mA	V _{DD} -0.5	-	-	V
V _{OL}	Output low voltage	I _{OL} =5mA	-	-	V _{SS} +0.4	V
I _{IH}	Input high current (Note 1)	-	-	-	10	μA
I _{IL}	Input low current (Note 1)	-	-	-	-10	μA
I _{OZH}	I/O tristate high current (Note 1)	-	-	-	50	μA
I _{OZL}	I/O tristate low current (Note 1)	-	-	-	-50	μA
I _{DDYN}	Dynamic supply current @ 16MHz	-	-	-	80	mA
I _{DDS}	Static supply current	-	-	-	10	mA

V_{DD}=5V±10% over full operating temperature range
Mil-Std-883, method 5005, subgroups 1, 2, 3
Note 1: Guaranteed but not tested at low temperature (-55°C)

Figure 18: Operating DC Electrical Characteristics

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Subgroup	Definition
1	Static characteristics specified in Figure 18 at +25°C
2	Static characteristics specified in Figure 18 at +125°C
3	Static characteristics specified in Figure 18 at -55°C
7	Functional characteristics specified in Figure 17 at +25°C
8A	Functional characteristics specified in Figure 17 at +125°C
8B	Functional characteristics specified in Figure 17 at -55°C
9	Switching characteristics specified in Figure 15 at +25°C
10	Switching characteristics specified in Figure 15 at +125°C
11	Switching characteristics specified in Figure 15 at -55°C

Figure 19: Definition of MIL-STD-883, Method 5005 Subgroups

PIN ASSIGNMENTS AND OUTLINES

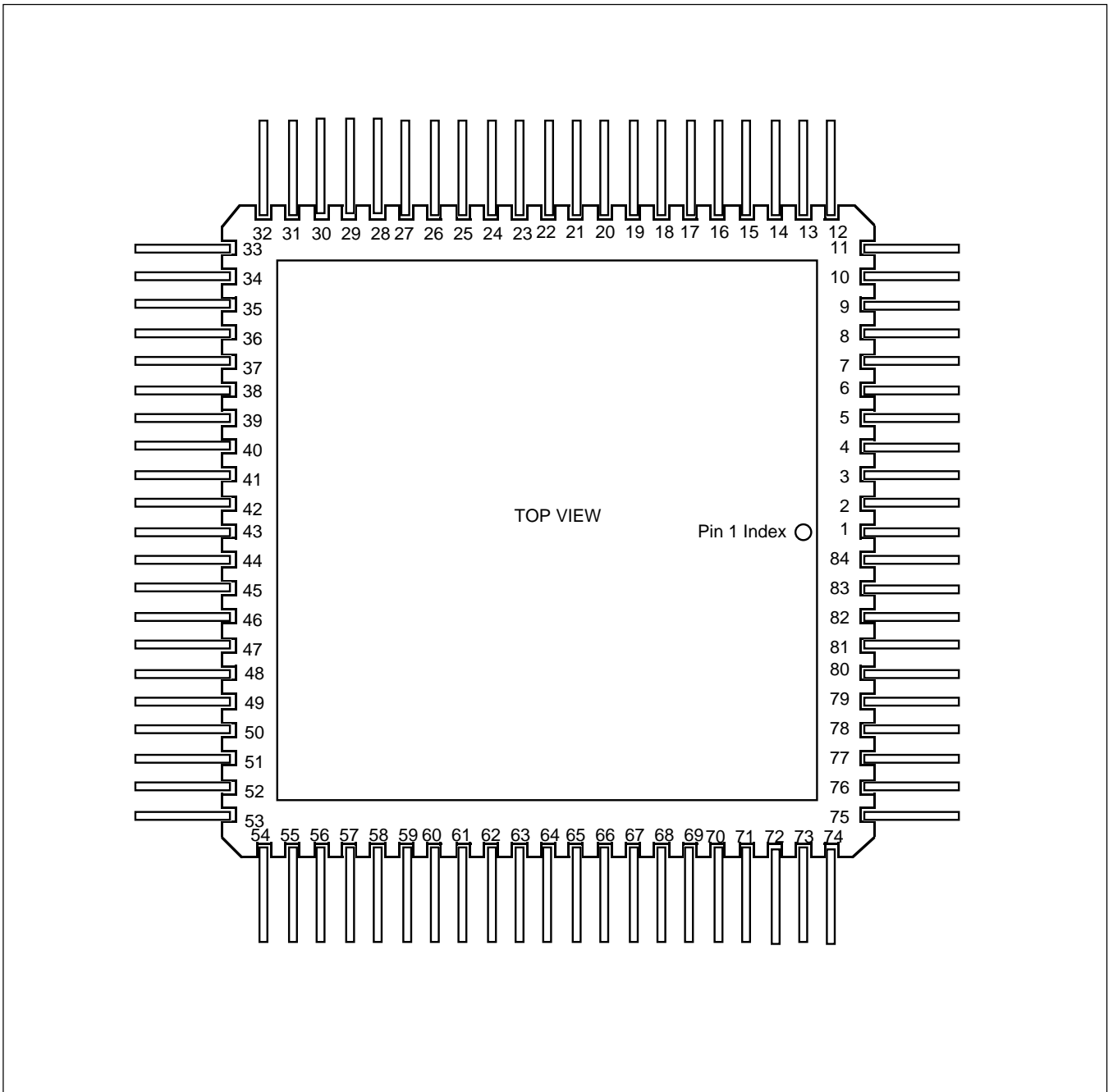
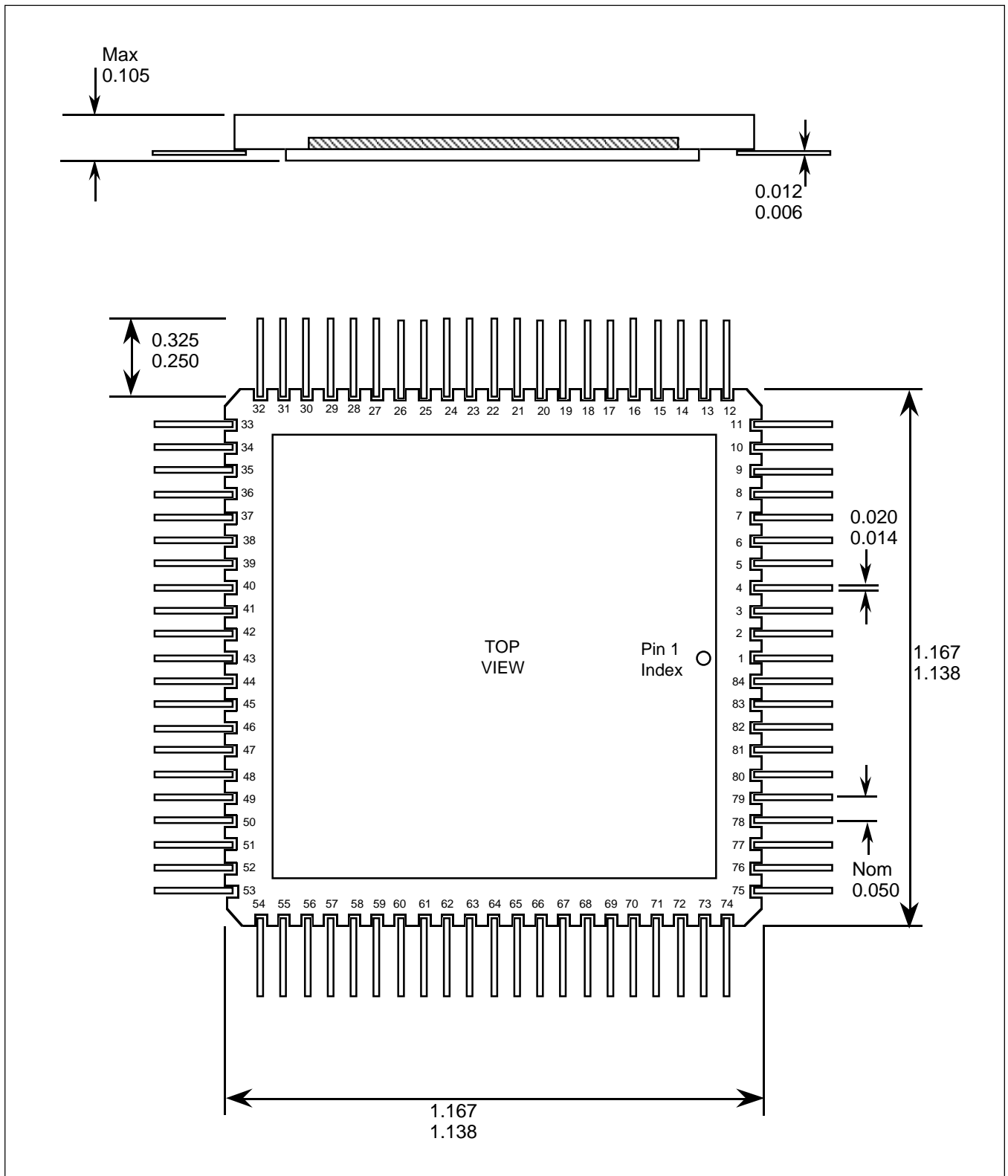


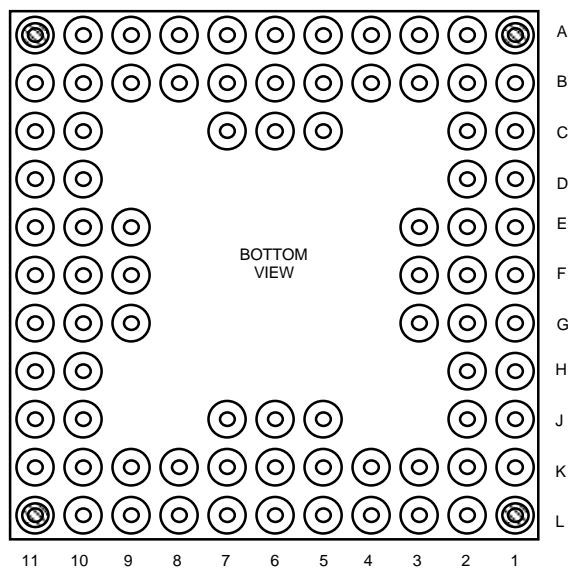
Figure 20: 84-Lead Flatpack - Package Style F

MA31753



NOTE: All dimensions shown in inches

Figure 21: 84-Lead Flatpack - Package Style F



A1		B11		F9		K2	
A2		C1		F10		K3	
A3		C2		F11		K4	
A4		C5		G1		K5	
A5		C6		G2		K6	
A6		C7		G3		K7	
A7		C10		G9		K8	
A8		C11		G10		K9	
A9		D1		G11		K10	
A10		D2		H1		K11	
A11		D10		H2		L1	
B1		D11		H10		L2	
B2		E1		H11		L3	
B3		E2		J1		L4	
B4		E3		J2		L5	
B5		E9		J5		L6	
B6		E10		J6		L7	
B7		E11		J7		L8	
B8		F1		J10		L9	
B9		F2		J11		L10	
B10		F3		K1		L11	

Figure 22: 84-Pin Grid Array - Package Style A

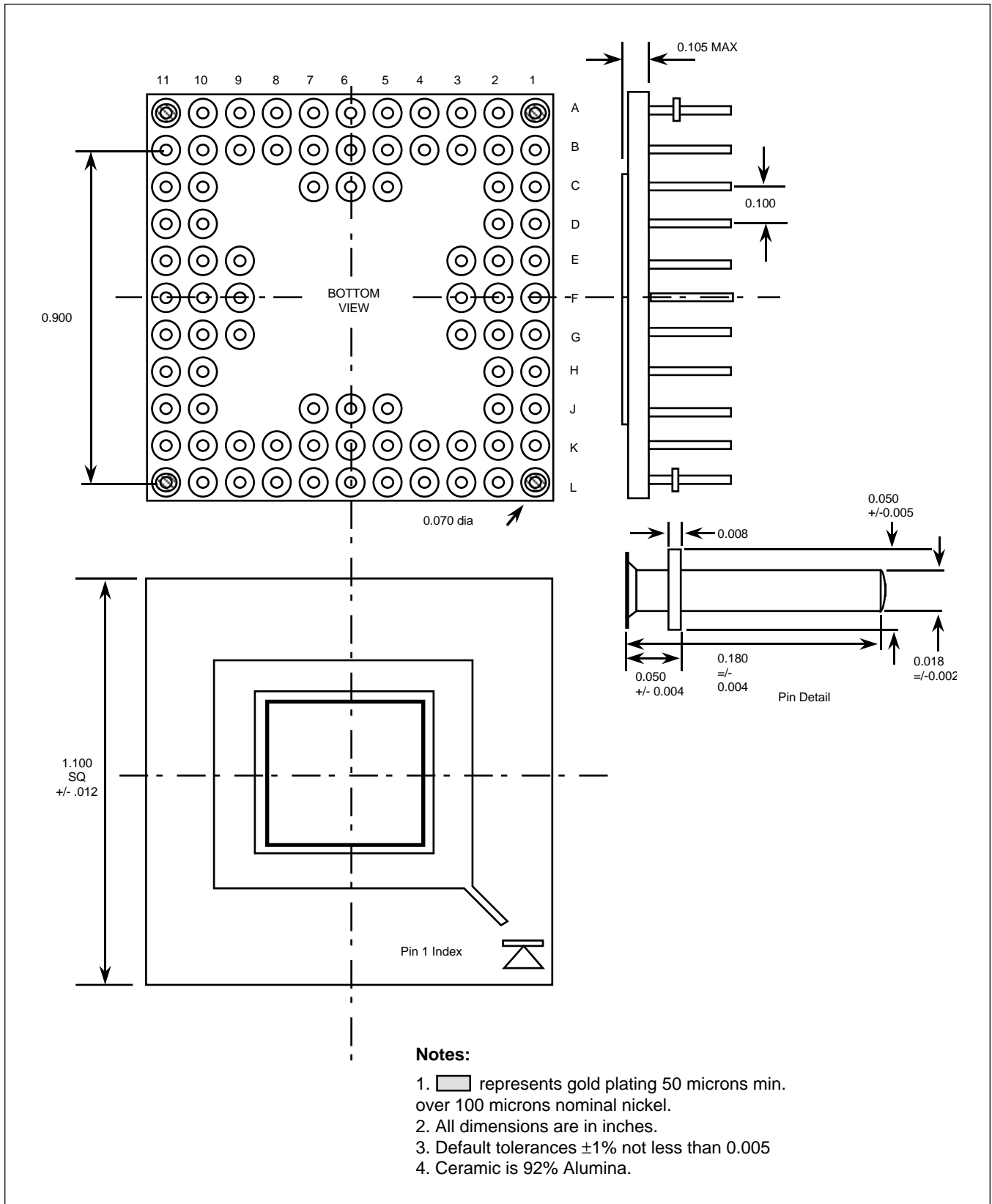


Figure 23: 84-Pin Grid Array - Package Style A

RADIATION TOLERANCE

Total Dose Radiation Testing

For product procured to total dose radiation levels, each wafer lot will be approved when all sample devices pass the total dose radiation test.

The sample devices will be subjected to the total dose radiation level (Cobalt-60 Source), defined by the ordering code, and must continue to meet the electrical parameters specified in the data sheet. Electrical tests, pre and post irradiation, will be read and recorded.

Dynex Semiconductor can provide radiation testing compliant with MIL STD 883 test method 1019, Ionizing Radiation (Total Dose).

Total Dose (Function to specification)*	3x10 ⁵ Rad(Si)
Transient Upset (Stored data loss)	1x10 ¹¹ Rad(Si)/sec
Transient Upset (Survivability)	>1x10 ¹² Rad(Si)/sec
Neutron Hardness (Function to specification)	>1x10 ¹⁵ n/cm ²
Single Event Upset**	<1x10 ⁻¹⁰ Errors/bit day
Latch Up	Not possible

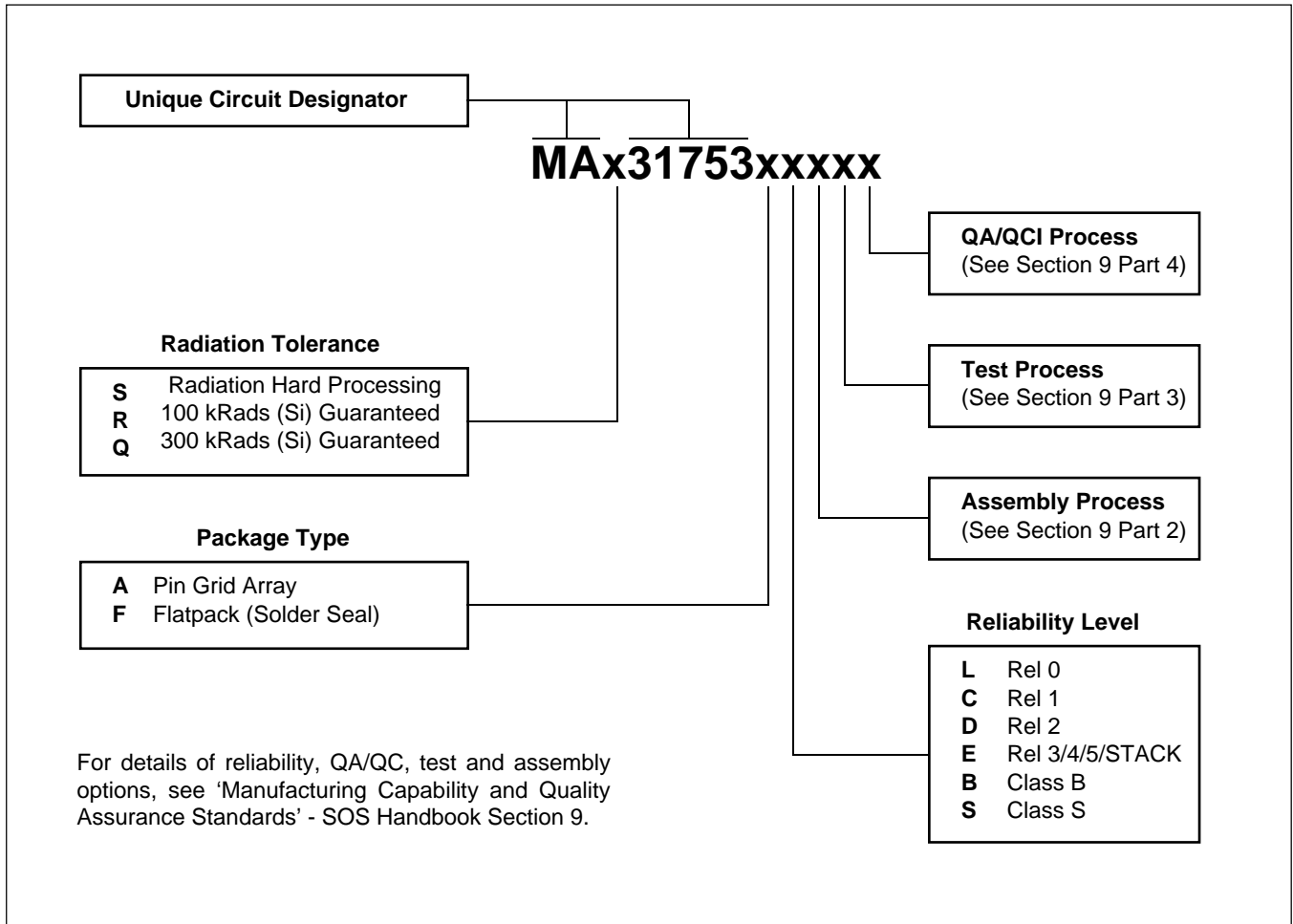
* Other total dose radiation levels available on request

** Worst case galactic cosmic ray upset - interplanetary/high altitude orbit

Figure 24: Radiation Hardness Parameters

MA31753

ORDERING INFORMATION



POWER ASSEMBLY CAPABILITY

The Power Assembly group was set up to provide a support service for those customers requiring more than the basic semiconductor, and has developed a flexible range of heatsink and clamping systems in line with advances in device voltages and current capability of our semiconductors.

We offer an extensive range of air and liquid cooled assemblies covering the full range of circuit designs in general use today. The Assembly group offers high quality engineering support dedicated to designing new units to satisfy the growing needs of our customers.

Using the latest CAD methods our team of design and applications engineers aim to provide the Power Assembly Complete Solution (PACs).

HEATSINKS

The Power Assembly group has its own proprietary range of extruded aluminium heatsinks which have been designed to optimise the performance of Dynex semiconductors. Data with respect to air natural, forced air and liquid cooling (with flow rates) is available on request.

For further information on device clamps, heatsinks and assemblies, please contact your nearest sales representative or Customer Services.



<http://www.dynexsemi.com>

e-mail: power_solutions@dynexsemi.com

HEADQUARTERS OPERATIONS
DYNEX SEMICONDUCTOR LTD
Doddington Road, Lincoln.
Lincolnshire. LN6 3LF. United Kingdom.
Tel: +44-(0)1522-500500
Fax: +44-(0)1522-500550

CUSTOMER SERVICE
Tel: +44 (0)1522 502753 / 502901. Fax: +44 (0)1522 500020

SALES OFFICES
Benelux, Italy & Switzerland: Tel: +33 (0)1 64 66 42 17. Fax: +33 (0)1 64 66 42 19.
France: Tel: +33 (0)2 47 55 75 52. Fax: +33 (0)2 47 55 75 59.
Germany, Northern Europe, Spain & Rest Of World: Tel: +44 (0)1522 502753 / 502901.
Fax: +44 (0)1522 500020
North America: Tel: (613) 723-7035. Fax: (613) 723-1518. Toll Free: 1.888.33.DYNEX (39639) /
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Target Information: This is the most tentative form of information and represents a very preliminary specification. No actual design work on the product has been started.

Preliminary Information: The product is in design and development. The datasheet represents the product as it is understood but details may change.

Advance Information: The product design is complete and final characterisation for volume production is well in hand.

No Annotation: The product parameters are fixed and the product is available to datasheet specification.

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